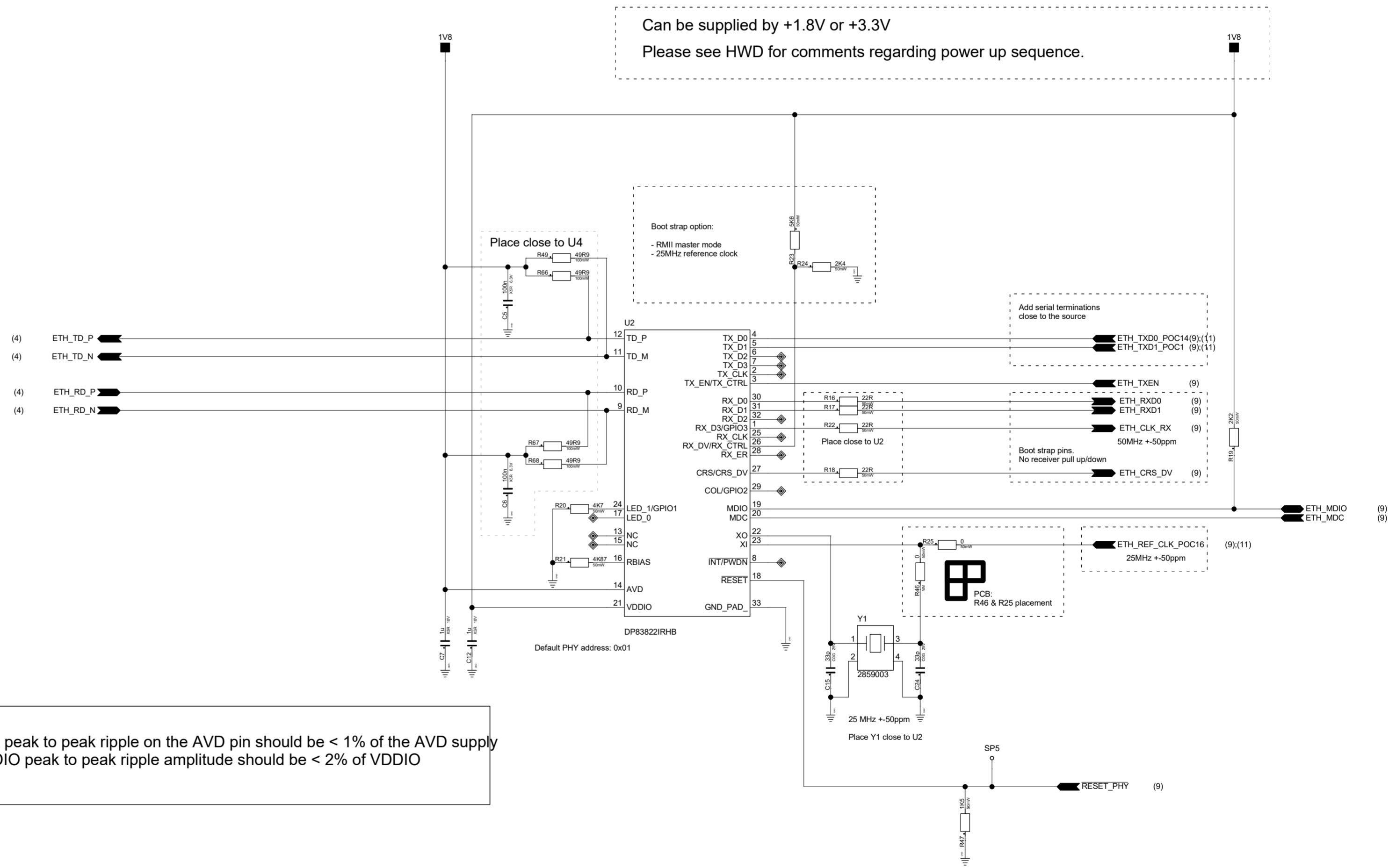


RMII MASTER 0201 VERSION



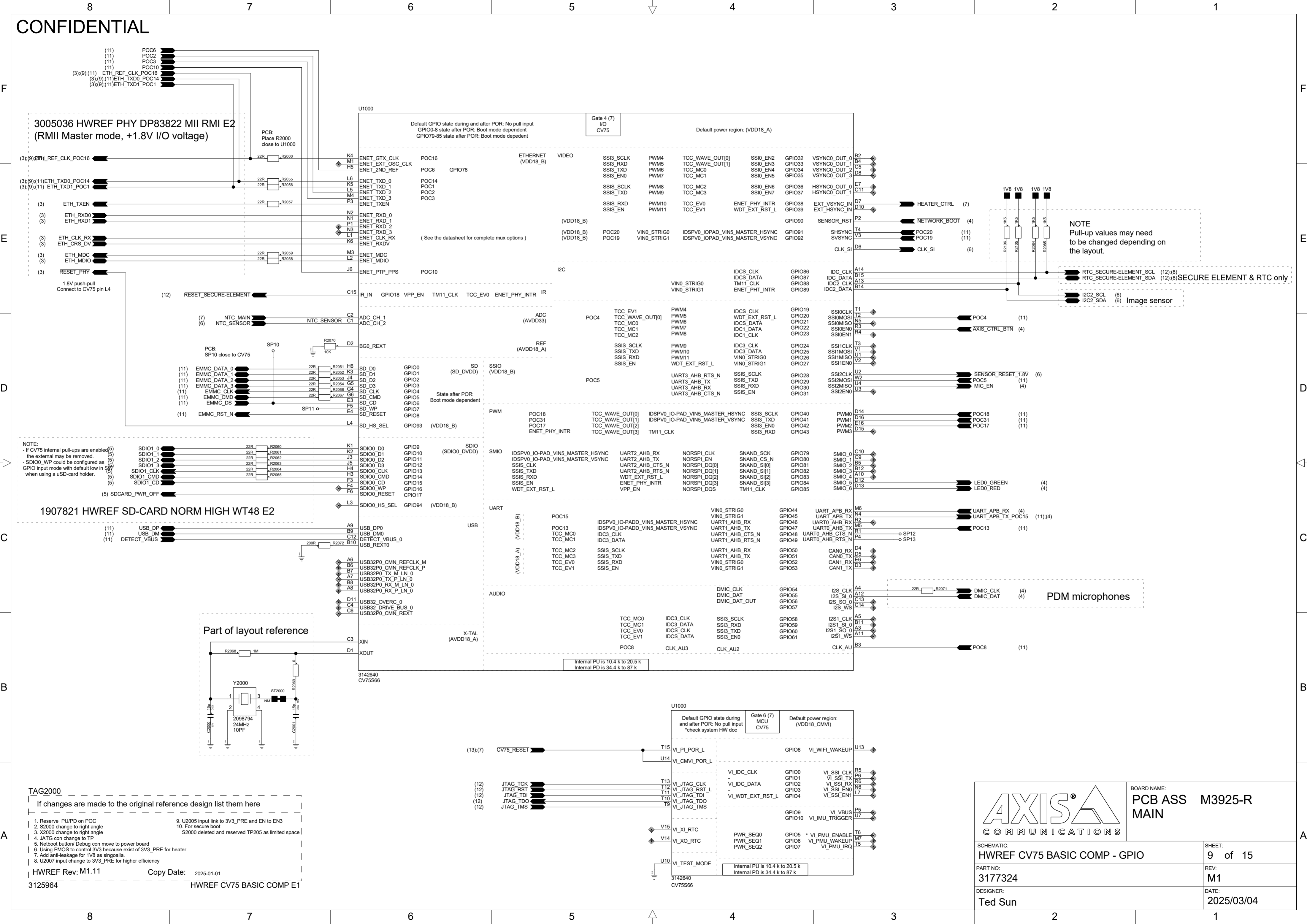
TI:
 Max peak to peak ripple on the AVD pin should be < 1% of the AVD supply
 VDDIO peak to peak ripple amplitude should be < 2% of VDDIO

TAG106
 If changes are made to the original reference design list them here

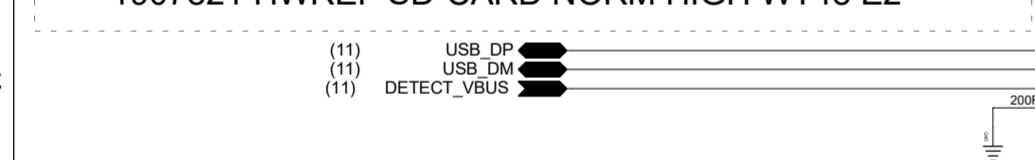
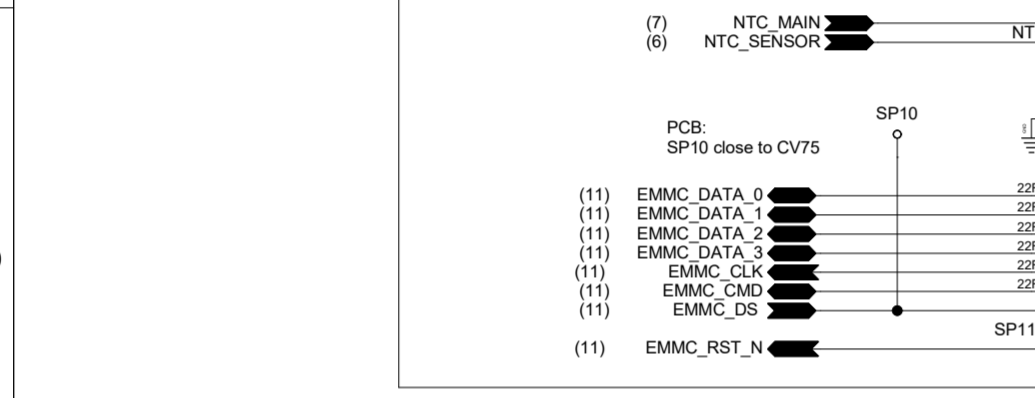
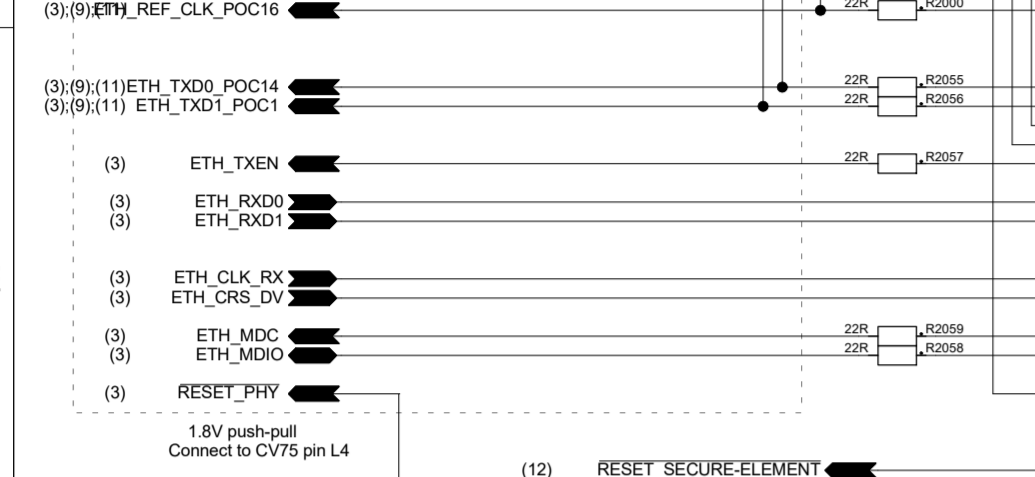
1. Used RMII 0201 version Master
2. Remove RJ45 con and Transformer / Caps to the power board

HWREF Rev: Mx.xx Copy Date: YYYY-MM-DD
 3005036 HWREF PHY DP83822 MII RMII E2

		BOARD NAME: PCB ASS M3925-R MAIN
SCHEMATIC: PHY	SHEET: 3 of 15	
PART NO: 3177324	REV: M1	
DESIGNER: Ted Sun	DATE: 2025/03/04	



3005036 HWREF PHY DP83822 MII RMI E2 (RMII Master mode, +1.8V I/O voltage)



TAG2000
If changes are made to the original reference design list them here
1. Reserve PU/PD on POC
2. S2000 change to right angle
3. X2000 change to right angle
4. JATG con change to TP
5. Netboot button/ Debug con move to power board
6. Using PMOS to control 3V3 because exist of 3V3_PRE for heater
7. Add anti-leakage for 1V8 as singola.
8. U2007 input change to 3V3_PRE for higher efficiency
9. U2005 input link to 3V3_PRE and EN to EN3
10. For secure boot S2000 deleted and reserved TP205 as limited space
HWREF Rev: M1.11 Copy Date: 2025-01-01
3125964 HWREF CV75 BASIC COMP E1

AXIS COMMUNICATIONS BOARD NAME: PCB ASS M3925-R MAIN
SCHEMATIC: HWREF CV75 BASIC COMP - GPIO SHEET: 9 of 15
PART NO: 3177324 REV: M1
DESIGNER: Ted Sun DATE: 2025/03/04